

# MOS FIELD EFFECT TRANSISTORS 2SK2369/2SK2370

# SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

#### **DESCRIPTION**

The 2SK2369/2SK2370 is N-Channel MOS Field Effect Transistor designed for high voltage switching applications.

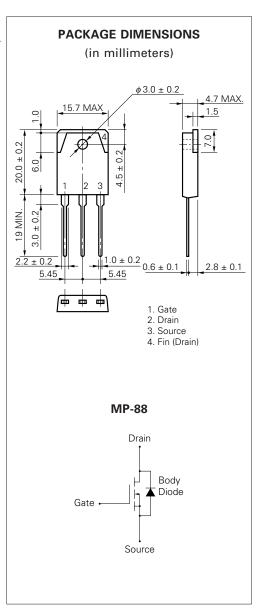
#### **FEATURES**

- Low On-Resistance
  - 2SK2369:  $R_{DS(on)} = 0.35 \Omega$  (Vgs = 10 V, ID = 10 A) 2SK2370:  $R_{DS(on)} = 0.4 \Omega$  (Vgs = 10 V, ID = 10 A)
- Low Ciss Ciss = 2400 pF TYP.
- High Avalanche Capability Ratings

#### ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

Voss	450/500	V
Vgss	±30	V
ID(DC)	±20	Α
$I_{D(pulse)}$	±80	Α
P <sub>T1</sub>	140	W
P <sub>T2</sub>	3.0	W
Tch	150	°C
T <sub>stg</sub> -	-55 to +150	°C
las	20	Α
Eas	285	mJ
	VGSS ID(DC) ID(pulse) PT1 PT2 Tch Tstg -	$\begin{array}{lllll} V_{GSS} & \pm 30 \\ I_{D(DC)} & \pm 20 \\ I_{D(pulse)} & \pm 80 \\ P_{T1} & 140 \\ P_{T2} & 3.0 \\ T_{ch} & 150 \\ T_{stg} & -55 \text{ to } +150 \\ I_{AS} & 20 \\ \end{array}$

- \* PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1 %
- \*\* Starting Tch = 25 °C, Rg = 25  $\Omega$ , Vgs = 20 V  $\rightarrow$  0



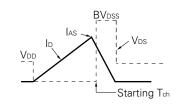


### ELECTRICAL COMPARA (STERISTICS (TA = 25 °C)

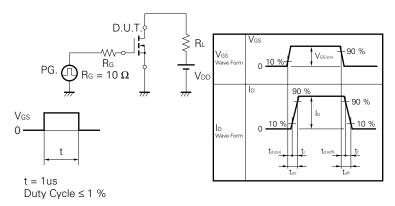
CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS	
Drain to Source On-State Resistance	RDS(on)		0.30	0.35	Ω	V <sub>GS</sub> = 10 V	2SK2369
			0.32	0.40		ID = 10 V	2SK2370
Gate to Source Cutoff Voltage	V <sub>GS(off)</sub>	2.5		3.5	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	
Forward Transfer Admittance	l yfs l	7.5			S	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 10 A	
Drain Leakage Current	IDSS			100	μΑ	V <sub>DS</sub> = V <sub>DSS</sub> , V <sub>GS</sub> = 0	
Gate to Source Leakage Current	Igss			±100	nA	V <sub>GS</sub> = ±30 V, \	/ <sub>DS</sub> = 0
Input Capacitance	Ciss		2400		pF	V <sub>DS</sub> = 10 V	
Output Capacitance	Coss		500		pF	V <sub>G</sub> S = 0	
Reverse Transfer Capacitance	Crss		45		pF	f = 1 MHz	
Turn-On Delay Time	td(on)		35		ns	ID = 10 A	
Rise Time	tr		60		ns	Vgs = 10 V	
Turn-Off Delay Time	td(off)		105		ns	V <sub>DD</sub> = 150 V	
Fall Time	tf		65		ns	$R_G = 10 \Omega R_L$	= 15 Ω
Total Gate Charge	QG		65		nC	ID = 20 A	
Gate to Source Charge	Qgs		15		nC	V <sub>DD</sub> = 400 V	
Gate to Drain Charge	QgD		30		nC	Vgs = 10 V	
Body Diode Forward Voltage	V <sub>F</sub> (S-D)		1.0		V	IF = 20 A, VGS	= 0
Reverse Recovery Time	trr		500		ns	IF = 20 A, VGS	= 0
Reverse Recovery Charge	Qrr		3.5		μC	di/dt = 50 A/μ	S

### Test Circuit 1 Avalanche Capability

# $\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \Omega \\ \text{VGS} = 20 - 0 \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{S} \\ \text{50 } \Omega \end{array}$



# Test Circuit 2 Switching Time

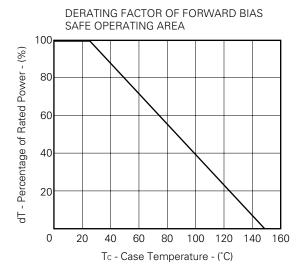


### **Test Circuit 3 Gate Charge**

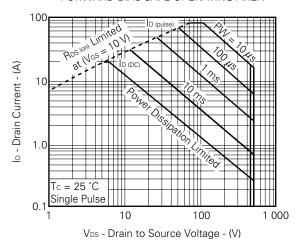
$$\begin{array}{c|c} D.U.T. \\ \hline \\ I_G = 2 \text{ mA} \\ \hline \\ V_{DD} \end{array}$$

The application circuits and their parameters are for references only and are not intended for use in actual design-in's.

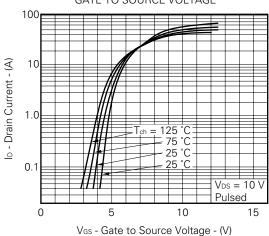
# 查询"TYRICAD"(中本的CTERISTICS (TA = 25 °C)

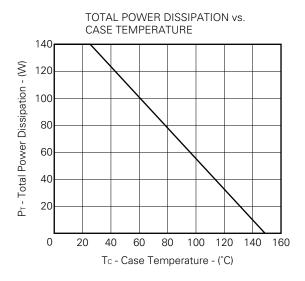


#### FORWARD BIAS SAFE OPERATING AREA

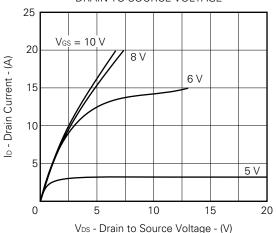


#### DRAIN CURRENT vs. GATE TO SOURCE VOLTAGE



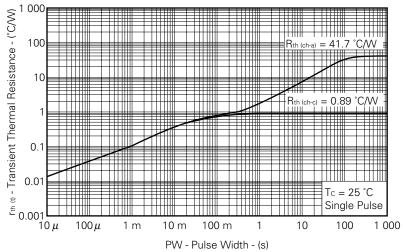


#### DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

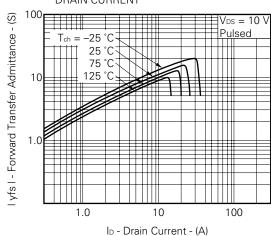


# 查询"2SK2369"供应商

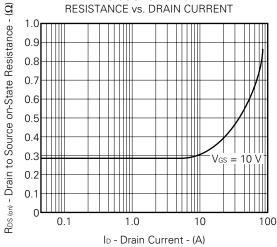




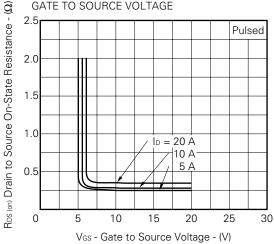
FORWARD TRANSFER ADMITTANCE vs. **DRAIN CURRENT** 



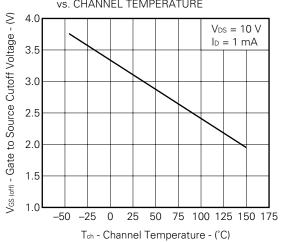
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

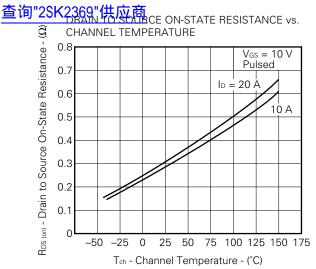


DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

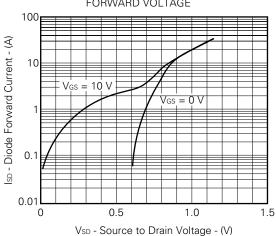


GATE TO SOURCE CUT OFF VOLTAGE vs. CHANNEL TEMPERATURE

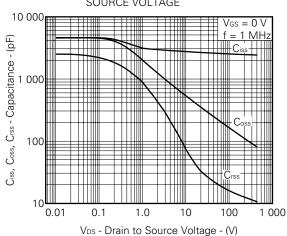




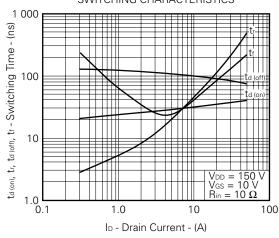
#### SOURCE TO DRAIN DIODE FORWARD VOLTAGE



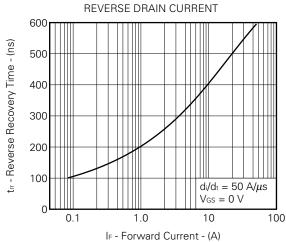
#### CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE



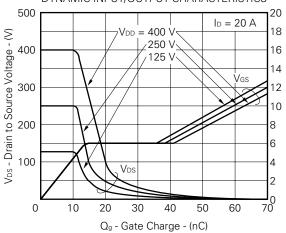
#### SWITCHING CHARACTERISTICS



# REVERSE RECOVERY TIME vs.



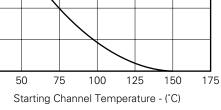
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



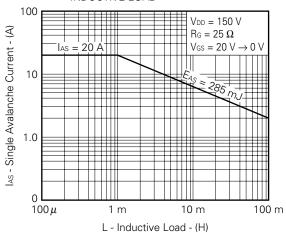
Vss - Gate to Source Voltage - (V)

0 L 25

# 查询"2SK2369"供应商 SINGLE AVALANCHE ENERGY vs. STARTING CHANNEL TEMPERATURE 300 EAS - Single Avalanche Energy - (mJ) las≤20 A $R_G = 25 \Omega$ $V_{GS} = 20 \; V \rightarrow 0$ $V_{DD} = 150 \text{ V}$ 200 100



#### SINGLE AVALANCHE ENERGY vs. INDUCTIVE LOAD



# 查询"BEFERENCK应商

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134
Power MOS FET features and application switching power supply.	TEA-1034
Application circuits using Power MOS FET.	TEA-1035
Safe operating area of Power MOS FET.	TEA-1037

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device is actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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